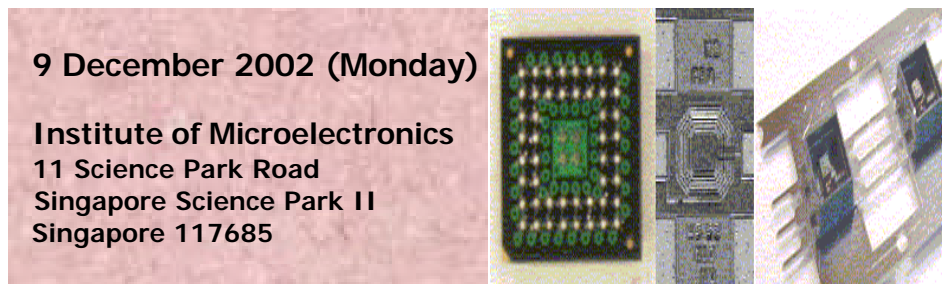


# ELECTRICAL DESIGN OF ADVANCED PACKAGING & SYSTEMS (EDAPS)

1<sup>ST</sup> Asian Workshop on Signal Integrity



## JOINT-ORGANIZERS



**Technically sponsored by:** IEEE CPMT TC-12 Subcommittee on Electrical Design, Modeling and Simulation

## OBJECTIVE

The EDAPS Workshop is to enhance the technical awareness in Asia region specifically in areas of package and system electrical design concepts, issues and challenges ahead for next generation electronic products.

## ADVANCED PROGRAMME

8.30 – 9.00 AM	Registration
9.00 – 9.10 AM	Opening Address by Chairman
9.10 – 9.50 AM	What happens on electronics packaging beyond several GHz signal? <i>Kanji Otsuka, Meisei University, Japan</i>
9.50 – 10.30 AM	Electrical modeling & simulation challenges for system-on-chip and system-in-package designs <i>Andreas Cagellaris, University of Illinois, USA</i>
10.30 – 10.50 AM	TEA-BREAK
10.50 – 11.30 AM	Modeling of arbitrary shaped multi-layer PCBs for high speed digital circuits <i>Jong-Gwan Yook, Yonsei University, Korea</i>
11.30 – 12.10 PM	Linear and nonlinear macro-modeling for system-level EMI/EMC assessment <i>Flavio Canavero, Politecnico di Torino, Italy</i>
12.10 – 2.00 PM	LUNCH
2.00 – 2.40 PM	High transfer speed packaging technology for mobile products <i>Gen Murakami, Hitachi Cable, Japan</i>
2.40 – 3.20 PM	Test strategies for high density packages <i>David Keezer, Georgia Tech, USA</i>
3.20 – 3.40 PM	TEA-BREAK
3.40 – 4.20 PM	SIMPACT Technology for 3D Module <i>Yasuhiro Sugaya, Matsushita Electric Industrial Co. Ltd</i>
4.20 – 5.00 PM	Power distribution modeling in multi-layer packages <i>Joungho Kim, KAIST, Korea</i>
5.00 – 6.00 PM	Panel Discussion: Design Challenges for System Integration
6.00 PM	Closing Remarks

# REGISTRATION

We welcome all to register early. Registration fee is as follow:

## Before and on 15 Nov '02 :

- Normal participants : S\$80.00
- Student participants : S\$40.00

## After 15 Nov '02 :

- Normal participants : S\$100.00
- Student participants : S\$40.00
- On-site registration : S\$100.00

Please send your registration form to [joanne@ime.a-star.edu.sg](mailto:joanne@ime.a-star.edu.sg) or fax 65-6774-5747

Name:	
Department:	
Company:	
Address:	
Tel/Fax/Email:	

For technical enquiry, please contact Cheah Soo Lan (email: [soolan@ime.a-star.edu.sg](mailto:soolan@ime.a-star.edu.sg), tel: +65 6770-5428). For administration enquiry, please contact Joanne Tan (email: [joanne@ime.a-star.edu.sg](mailto:joanne@ime.a-star.edu.sg), tel: +65 6770-5328) for more details.

## Payment

Mail form and payment to:

**Institute of Microelectronics, 11 Science Park Road, Singapore Science Park II, Singapore 117685. Attention: Mahadevan K Iyer/Joanne Tan.** Student must include proof of full-time enrolment to obtain student fees.

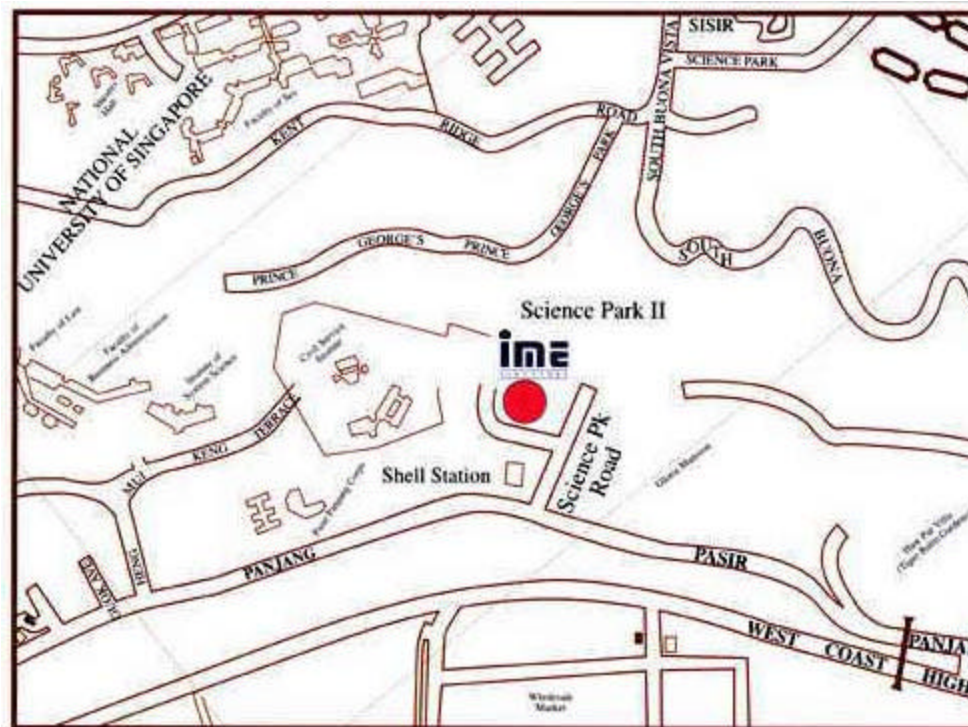
☐ Please pay via cash/cheque/bankdraft in Singapore Dollars or US Dollars - payable to **Institute of Microelectronics**

**Foreign Attendees Only:** For hotel accommodation, we recommend you to stay at Grand Copthorne Waterfront Hotel (Singapore) where 4<sup>th</sup> Electronic Packaging Technology Conference (EPTC) is held from 10 – 12 Dec '02. Please go to [www.grandcopthorne.com.sg](http://www.grandcopthorne.com.sg) and [ewh.ieee.org/soc/cpmt/singapore/eptc2002/](http://ewh.ieee.org/soc/cpmt/singapore/eptc2002/) for hotel and EPTC 2002 enquiry respectively.

# WORKSHOP LOCATION

The EDAPS Workshop will be held in the Institute of Microelectronics (Auditorium) situated in the Science Hub of Singapore where science, research and technology environment takes place.

The location is at 11 Science Park Road, Singapore Science Park II, Singapore 117685. You can take our regular Singapore Science Park shuttle bus from Clementi MRT to IME (and vice versa) from 7.30am to 7.30pm.



# PROGRAMME COMMITTEE

<b>Chairman</b>	:	Mahadevan K Iyer Institute of Microelectronics
<b>Co-Chairmans</b>	:	Toshio Sudo Toshiba Corporation
	:	Jungho Kim KAIST Korea
<b>Committee Members</b>	:	Albert Lu Singapore Institute of Manufacturing Technology
		Allan Chin Agilent Technologies Singapore Pte Ltd
		Arokiaswami Alphones, <i>School of EEE</i> Nanyang Technological University
		B G Guruprasad ST Assembly Test Services Ltd
		Cheah Soo Lan Institute of Microelectronics
		Daniel Chan ST Assembly Test Services Ltd
		Ho Peng Chin Micron Semiconductor Asia Pte Ltd
		Lee Jun Woo KAIST Korea
		Li Er Peng Institute of High Performance Computing
		Low Hong Guan United Test and Assembly Center Ltd
		Mihai Dragos Rotaru Institute of Microelectronics
		Ooi Ban Leong National University of Singapore
		Tee Onn Chong Intel Electronics (Malaysia) Sdn Bhd

Wong Wui Weng  
Advanced Micro Devices (Singapore) Pte Ltd

Yeo Yong Kee  
Georgia Institute of Technology

# INTERNATIONAL ADVISORY COMMITTEE

Alina Deutsche	:	IBM Corporation, USA
Andreas Cangellaris	:	University of Illinois, USA
Andreas Weisssharr	:	Ohio State University, USA
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Tawfik Arabi	:	Intel Corporation, USA